



IFW

**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Jun-ichiro FURIHATA et al.

Group Art Unit: 1772

Application No.: 10/690,541

Examiner: J. RHEE

Filed: October 23, 2003

Docket No.: 108868.01

For: METHOD OF PRODUCING A BONDED WAFER AND THE BONDED WAFER

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the March 30, 2004, Office Action, the following is submitted:

**Amendments to the Claims** are reflected in the listing of claims; and

**Remarks.**